SiC Power MOSFET N-Channel Enhancement Mode

Features

- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitances
- Avalanche Ruggednes

Applications

- Solar Inverters
- Switch Mode Power Supplies
- **Batterry Chargers**

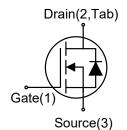






Package Marking and Ordering Information

Ordering Part Number	Package	Brand		
IPD80R280P7ATMA1	TO-252-2L	HXY MOSFET		



Absolute Maximum Ratings

Symbol	Parameter	Value	Unit	Test Conditions
V_{DSmax}	Drain - Source Voltage	800	V	
V_{GSmax}	Gate - Source Voltage (Absolute maximum values)	-8/+22	V	
V_{GS}	Gate - Source Voltage	-4/+18	V	
	Continuous Drain Current	14.3	А	T _C = 25°C
I _D Continuous Drain Curren	Continuous Diam Current	8.2		T _C = 100°C
I _{D(pulse)}	Pulsed Drain Current	25	А	Pulse width t _P limited by T _{jmax}
P _{TOT}	Power Dissipation	71	W	T _C = 25°C
T_{J} , T_{stg}	Operating Junction and Storage Temperature	-55 to +175	°C	

$\bullet \mbox{Example}$ of acceptable $V_{\mbox{\scriptsize GS}}$ waveform



Electrical Characteristics (T_C = 25°C unless other wise specified)

	Parameter	Value			1114	T 10 III
Symbol		min.	typ.	max.	Unit	Test Condition
Static Cha	aracteristics					
V_{DSS}	Drain-source breakdown voltage	800	-	-	V	V _{GS} =0V, I _D =100uA
V _{GS(th)}	Gate threshold voltage	2	3	4	V	$V_{DS}=V_{GS}$, $I_D=0.43$ mA
						V _{DS} =800V,V _{GS} =0V
I _{DSS}	Zero gate voltage drain current	-	1	5	μΑ	T _C =25°C
		-	5	-		T _C =175°C
I _{GSS}	Gate-source leakage current	-		100	nA	V _{GS} =18V,V _{DS} =0V
						V _{GS} =18V, I _D =3.6A,
$R_{DS(on)}$	Drain-source on-state resistance	-	230	269	mΩ	T _J =25°C
			276			T _J =175°C
В	Dunin common ou otata unalistance	-	295	360	mΩ	V _{GS} =15V, I _D =3.6A,
R _{DS(on)} Drain-source of	Drain-source on-state resistance	-	350	-		Tյ=25°C Tյ=175°C
Dynamic (Characteristics					
C _{iss}	Input Capacitance	-	287.9	-		V_{DS} = 600V V_{GS} = 0V T_{J} = 25°C V_{AC} = 25mV f = 1MHz
C _{oss}	Output Capacitance	-	21.84	-	pF	
C_{rss}	Reverse Transfer Capacitance	-	2.31	-		
Q_{G}	Gate Total Charge	-	14.1	-		V _{DS} = 600V
Q_{gs}	Gate-Source charge	-	2.78	-	nC	$V_{GS} = -4/18V$ $I_{D} = 3.6A$
Q_{gd}	Gate-Drain charge	-	8.97	-		
E _{ON}	Turn-On Switching Energy	-	42.5	-		
E _{OFF}	Turn-Off Switching Energy	-	7.1	-	μJ	V _{DD} = 600V
$t_{d(on)}$	Turn-on delay time	-	4.3	-		$V_{GS} = -4/+18V$
t _r	Rise time	-	9	-	ns	$I_D = 3.6A$ $R_G = 5\Omega$ $L = 1 \text{ mH}$ $T_J = 25^{\circ}\text{C}$
$t_{d(off)}$	Turn-off delay time	-	8.6	-		
t _f	Fall time	-	30.6	-		
R_{G}	Gate resistance	-	3.8	-	Ω	V _{AC} = 25mV, f=1MHz

Body Diode Characteristics

V_{SD}	Body Diode Forward Voltage		3		V	V _{GS} = -4V,I _{SD} =1.8A, T _J =25°C
V _{SD}	Body Diode Polward Voltage		2.7		V	V _{GS} = -4V,I _{SD} =1.8A, T _J =175°C
t _{rr}	Body Diode Reverse Recovery Time	-	52	-	ns	
Q _{rr}	Body Diode Reverse Recovery Charge	-	21.8	-	nC	
E _{REC}	Reverse Recovery Energy	1	0.45	-	uJ	V _R = 600V, V _{GS} = -4V
I _{rrm}	Peak Reverse Recovery Current	•	2.46	-	А	I _D = 3.6A di/dt = 1000A/μs T _J = 25° C
t _A	Charge Time	-	13.3	-	ns	·
t _B	DisCharge Time	-	2.6	-	ns	

Thermal Characteristics

Symbol	Parameter	Тур.	Unit	Test Conditions
R _{thJC}	Thermal Resistance from Junction to Case	2.1	°0.044	
R _{thJA}	Thermal Resistance From Junction to Ambient	40	°C/W	



Typical Performance

Fig 1. Output Characteristic (T_J=-55°C)

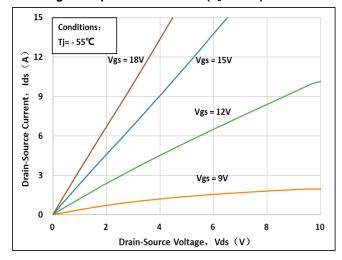


Fig 3. Output Characteristic (T_J=175°C)

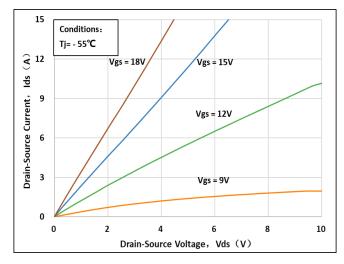


Fig 5: Rds(on) vs. Temperature

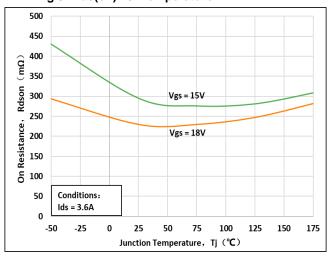


Fig 2. Output Characteristic (T_J=25°C)

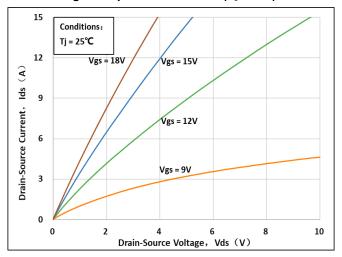


Fig 4: Rdson Vs Ids Characteristic

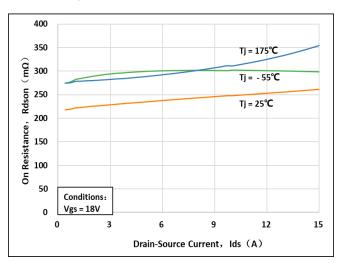
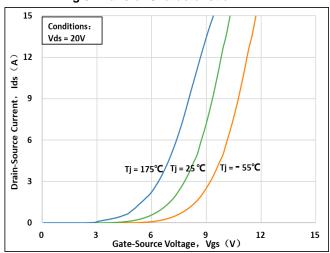


Fig 6: Transfer Characteristic



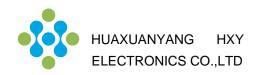


Fig 7: Body-diode Characteristic (T_J=-55°C)

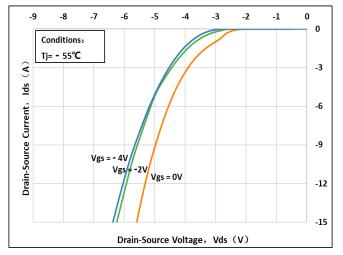


Fig 8: Body-diode Characteristic (T_J=25°C)

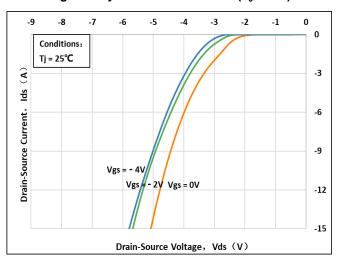


Fig 9: Body-diode Characteristic (T_J=175°C)

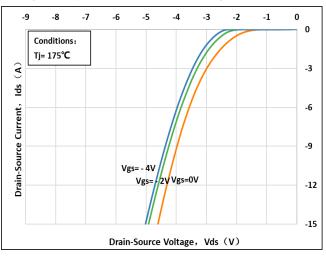


Fig 10: V_{TH} Vs T_J Temperature Characteristic

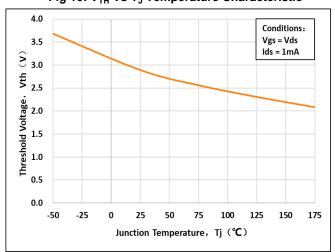


Fig 11: 3rd Quadrant Characteristic(T_J=-55°C)

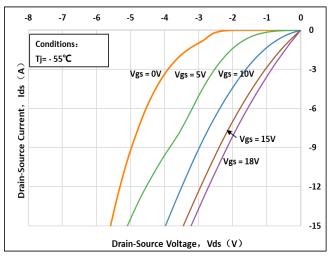


Fig 12: 3rd Quadrant Characteristic(T_J=25°C)

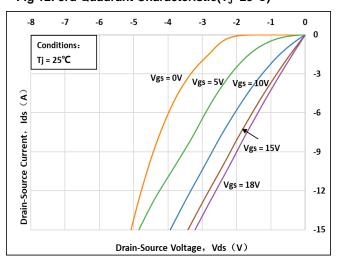




Fig 13: 3rd Quadrant Characteristic(T_J=175°C)

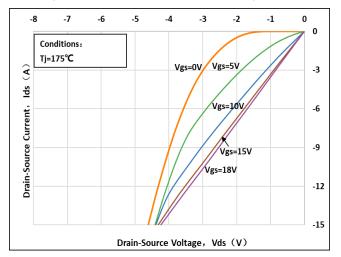


Fig 15: Drain Current vs.Case Temperature

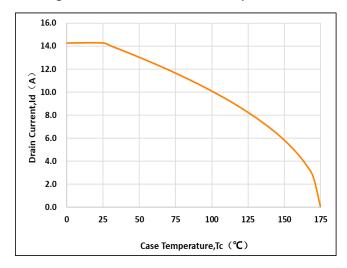


Fig 17: Capacitance Characteristics

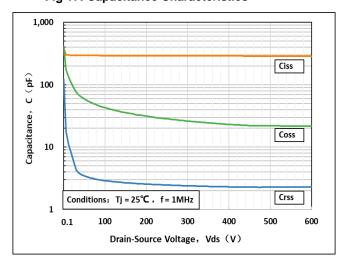


Fig 14: Gate Charge Characteristics

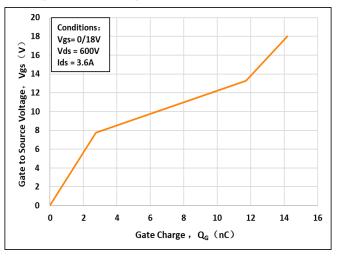


Fig 16: Safe Operating Area

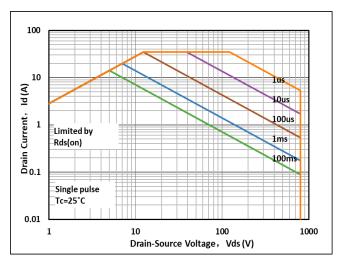
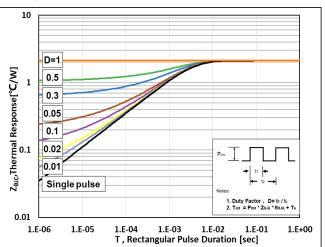


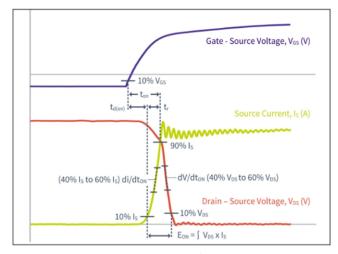
Fig 18: Transient Thermal Impedance



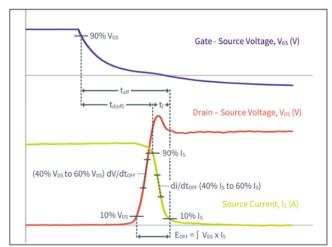


Test Circuit & Waveform

Figure A. Definition of switching times



Turn-on Transient Definitions



Turn-off Transient Definitions

Figure B. Dynamic test circuit

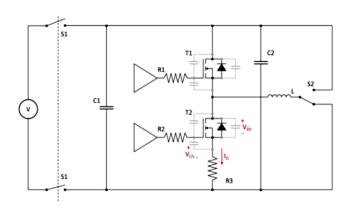
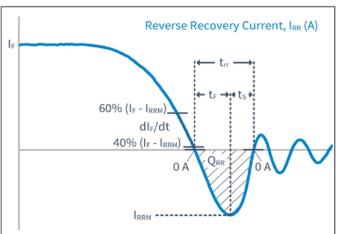


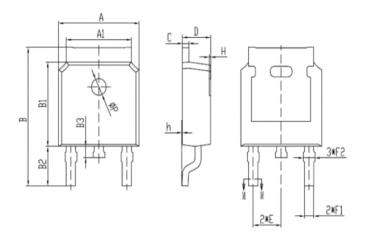
Figure C. Definition of body diodeswitching characteristics



Reverse Recovery Definitions

Package Dimensions

Package TO-252-2L





11年日	规范(mm)				
项目	MIN	MAX			
A	6.50	6.70			
A1	5.16	5.46			
В	9.77	10.17			
B1	6.00	6.20			
B2	2.60	3.00			
В3	0.70	0.90			
С	0.45	0.61			
D	2.20	2.40			
Е	2.186	2.386			
F1	0.67	0.87			
F2	0.76	0.96			
Н	0.00	0.30			
h	0.00	0.127			
L	6.50	6.70			
фР	1.10	1.30			

Attention

- Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.
- HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.
- Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc.

 When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.